

A

B

C

D

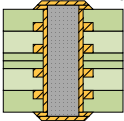
Layer Stack Legend

Material	Layer	Thickness	Type	Gerber	Weight
	Top Overlay		Legend	GTO	
Surface Material	Top Solder	0.001mm	Solder Mask	GTS	
Nickel, Gold	Top Surface Finish	0.001mm	Surface Finish		
CF-004	Top Layer	0.035mm	Signal	GTL	1oz
Prepreg		0.110mm	Dielectric		
CF-004	Int1(GND)	0.070mm	Signal	G1	2oz
Core		0.110mm	Dielectric		
CF-004	Int2(Sign)	0.070mm	Signal	G2	2oz
Prepreg		0.065mm	Dielectric		
Prepreg		0.065mm	Dielectric		
CF-004	Int3 (Sign)	0.070mm	Signal	G3	2oz
Core		0.110mm	Dielectric		
CF-004	Int4(GND)	0.070mm	Signal	G4	2oz
Prepreg		0.110mm	Dielectric		
CF-004	Bottom Layer	0.035mm	Signal	GBL	1oz
Nickel, Gold	Bottom Surface Finish	0.001mm	Surface Finish		
Surface Material	Bottom Solder	0.001mm	Solder Mask	GBS	
	Bottom Overlay		Legend	GBO	

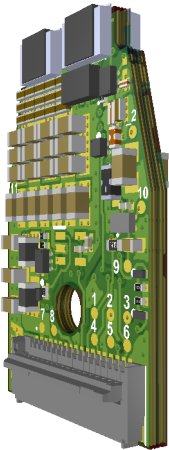
Total thickness: 0.924mm

Through Hole Vias: filled with Resin, Via in Pad, Capped
Microvias: Filled with conductive material, Capped

Via Type Type 7 (Scale 16:1)



Realistic View



Eidgenössische Technische Hochschule Zürich
Swiss Federal Institute of Technology Zurich

Laboratory: IIS

Date: 17/07/2025 14:42

Rev: 1.0

Variation fabrication

File: PULSER_MAN.PCBDwf

Project: HELIOS-R

LD Pulser - Manufacturing Sheet

Drawn By: villanif

Checked By: *

Sheet: 1 / 2

A

B

C

D

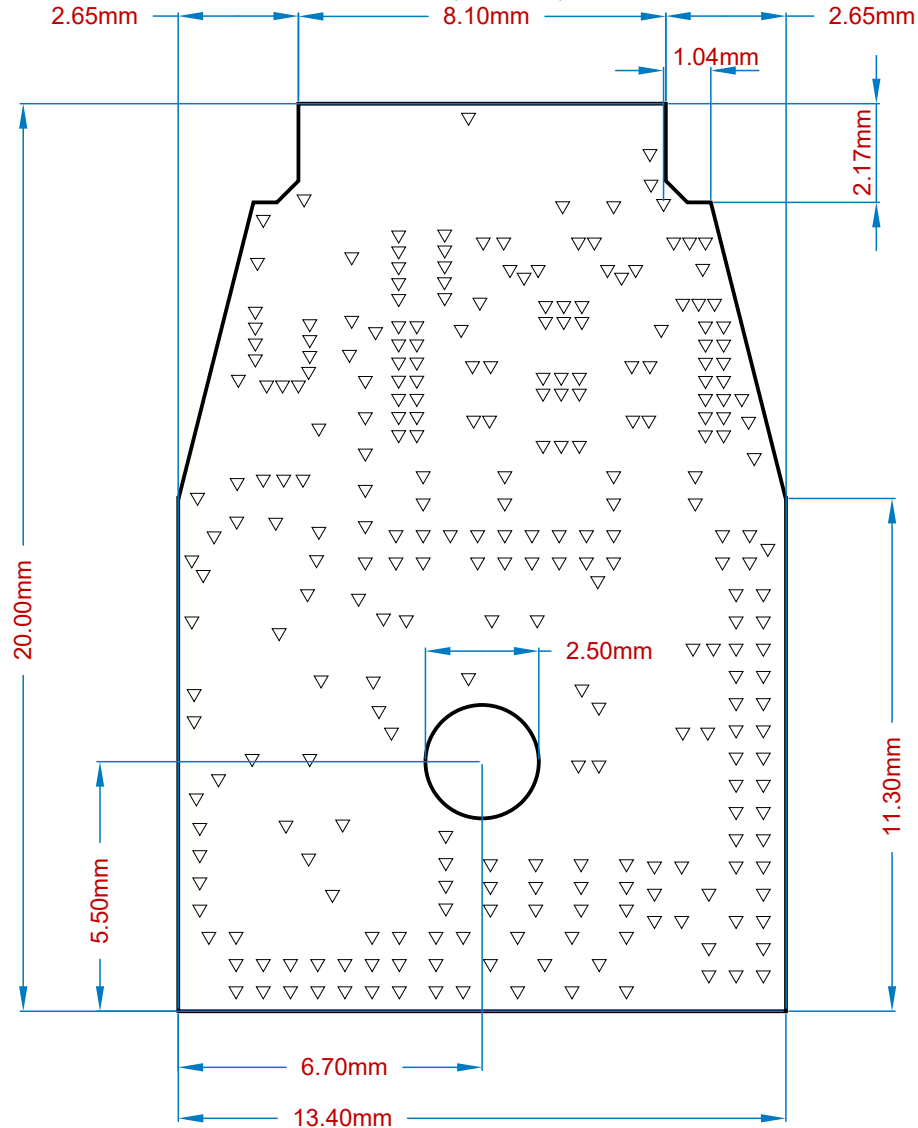
A

B

C

D

Drill View vias top-bottom (Scale 6:1)



Drill Table - top to bottom

Symbol	Count	Hole Size	Plated	Drill Layer Pair	Via / Pad
▽	278	0.20mm	Plated	Top Layer - Bottom Layer	Via
278 Total					

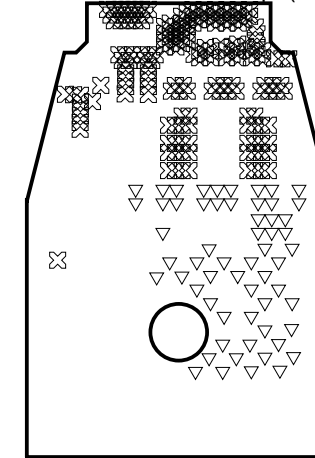
Drill Table - microvias - top layer

Symbol	Count	Hole Size	Plated	Drill Layer Pair	Via / Pad
⊗	180	0.15mm	Plated	[UVIA] Top Layer - Int1(GND)	Via
▽	59	0.20mm	Plated	[UVIA] Top Layer - Int1(GND)	Via
239 Total					

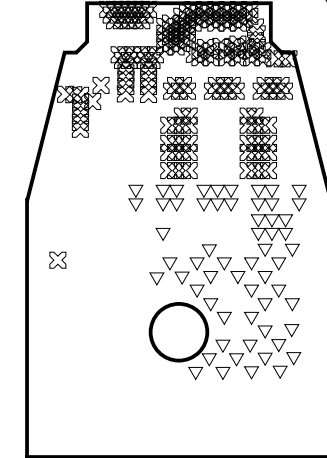
Drill Table - microvias - bottom layer

Symbol	Count	Hole Size	Plated	Drill Layer Pair	Via / Pad
⊗	182	0.15mm	Plated	[UVIA] Int4(GND) - Bottom Layer	Via
▽	45	0.20mm	Plated	[UVIA] Int4(GND) - Bottom Layer	Via
227 Total					

Drill View microvias top (Scale 3:1)



Drill View microvias bottom (Scale 3:1)

**ETH**Eidgenössische Technische Hochschule Zürich
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LD Pulser - Manufacturing Sheet

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Sheet: 2 / 2